Since 2007, Eseye has led the way in IoT connectivity, launching the world’s first multi-IMSI SIM in 2010. The latest AnyNet+ eUICC SIM combines the best of Eseye’s multi-IMSI technology with an enhanced approach to the eUICC standard, giving customers the most advanced IoT connectivity solution on the market today.

The AnyNet+ SIM is uniquely designed with multiple bootstrap profiles (multi-IMSI). When coupled with Eseye’s proprietary Connectivity Management Platform and extensive list of network interconnects, the AnyNet+ SIM card can rotate to find optimum coverage on another network, should an individual profile fail to connect. Most importantly, the AnyNet+ SIM can be localized OTA to a local network using the ‘step 2 profile’, allowing customers to avoid legal and regulatory restrictions such as permanent roaming. The result is the ability to deliver near 100% connectivity out of the box from a single product SKU.

Furthermore, the AnyNet+ SIM comes 5G and NB-IoT ready and delivers maximised 2G, 3G or 4G cellular coverage across GSM, LTE including CAT M networks, reinforced by our extensive global MNO interconnects. This unique combination delivers a robust, high performing and future proofed IoT solution for your business.

With the power to manage your global device estate from one single centralised management console, you stay in complete control of your IoT deployment. With zero-touch management and advanced security features including private APN and VPN connections, the AnyNet+ SIM also reduces both the risk and TCO of your global IoT deployment.
Features

- Multiple bootstrap IMSIs to enable autonomous network switching
- Advanced, intelligent eUICC eSIM with full multi-IMSI capability
- Integration with Eseye Connectivity Management Platform to seamlessly manage network switching
- Private APN, VPN and Fixed IPs to provide complete security
- Simple SIM estate Management via Central SIAM Console
- Full suite of security features, including IMEI locking and bespoke firewall
- Real-time billing alerts and cost management
- Provides real-time SIM location-based services

Benefits

- **Ubiquitous global connectivity:** achieve over 99.8% device connectivity uptime across more than 190 countries globally
- **Out-of-the-box, zero-touch provisioning:** automatic over-the-air (OTA) connection and setup of the device with no on-site configuration
- **Central management:** one global point of contact for service, support and billing for all IoT device connectivity; no need for multiple MNO contracts and associated support agreements
- **Improved connectivity resilience:** Fully eUICC compliant eSIM with multi-IMSI capability to allow complete autonomy to switch networks whilst preserving multiple fallback bootstraps in the event of an OTA switch under eUICC
- **Future proofed SIM technology:** 5G and NB-IoT ready with support for LTE networks, which will benefit applications using all 4G networks including Cat-M1 Devices
- **Flexible integration:** multiple out-of-the-box integration options with Cloud providers and device manufacturers
SIM specification

SIM type
- Standard M2M grade 2FF, 3FF card or MFF2 embedded (eSIM)
- M2M grade MFF2 embedded cards and specifications are available on request

MFF2 operation

<table>
<thead>
<tr>
<th>Operating Temperature Range</th>
<th>MFF2 EMBEDDED SIM</th>
</tr>
</thead>
<tbody>
<tr>
<td>-40°C to +85°C</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Temperature Humidity Bias (THB)</th>
<th>To JESD22-A101</th>
</tr>
</thead>
</table>

<table>
<thead>
<tr>
<th>Storage Temperature</th>
<th>-40°C to +125°C</th>
</tr>
</thead>
</table>

<table>
<thead>
<tr>
<th>Vibration Variable Frequency (VVF)</th>
<th>To JESD22-B103</th>
</tr>
</thead>
</table>

MFF2 power
- Supply voltage range: 1.62 V to 3.3 V

MFF2 package dimensions
- Weight: 0.17g

Provisioning & management
- Eseye SIAM portal (account required). See more here
- API available. See more here

Features
- SMS/MMS/USSD/CSD
- SIMID barcode

Security
- Private APN
- APN Firewall
- Side channel attack detection: (SPA, DPA)
- Encrypted storage: code, keys and data
- Blocking available on IMEI, location, country and services
- Flexible feature enablement/ disablement

Memory & data storage
- Non-Volatile Memory (NVM): 512 kB
- Write/erase time (max.): 2.3 ms
- Data retention time (min.): over 10 years at -40 to +85°C
- High stress memory (HSM) supports >2M E/W cycles per file

SIM PIN definitions

For full details on the layout of Embedded SIMs see below

<table>
<thead>
<tr>
<th>PIN</th>
<th>SIM CARD (2FF/3FF)</th>
<th>EMBEDDED SIM (MFF2)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>VCC</td>
<td>GND</td>
</tr>
<tr>
<td>2</td>
<td>RST</td>
<td>NC</td>
</tr>
<tr>
<td>3</td>
<td>CLK</td>
<td>i/O</td>
</tr>
<tr>
<td>4</td>
<td>GND</td>
<td>NC</td>
</tr>
<tr>
<td>5</td>
<td>VPP</td>
<td>NC</td>
</tr>
<tr>
<td>6</td>
<td>i/O</td>
<td>CLK</td>
</tr>
<tr>
<td>7</td>
<td>-</td>
<td>RST</td>
</tr>
<tr>
<td>8</td>
<td>-</td>
<td>VDD</td>
</tr>
</tbody>
</table>

Available to order via email to sales@eseye.com

Minimum order quantity: 1 SIM for 2FF / 3FF and 200 SIMs MFF2.

Lead time: we aim to process all 2FF / 3FF SIM card orders on the day of order (if ordered before 3PM GMT). Please note, these specifications may be subject to change without prior notice.

Conforming to the JEDEC specification, ideal for automated soldering as part of manufacturing package thickness shall not exceed 1.0mm. An index marker will be visible on the exposed metal heat feature located at the terminal 1 corner. The topside terminal 1 shall be indicated by a marked feature. The exposed metal heat feature (exposed die pad) of the package is either electrically connected internally to ground or it is not electrically connected within the package.

The electrical handling of the JEDEC terminals shall be as defined in ETSI TS 102 221